Our aluminum heat sinks are designed in a way that is the most cost effective solution for cooling a majority of electronic devices. We use 6061 aluminum alloy, which with excellent thermal and mechanical properties. Heat sink parts are made with all features necessary for cooling electronic components, such as audio amplifier, insulated-gate bipolar transistor (IGBT), silicon controlled rectifier (SCR), metaloxide-semiconductor field-effect transistor (MOSFET), and so on. Fins are tapered with engineered sizes to achieve the maximum heat dissipation.

We carry a full length of 6 feet and cut to **your specified length (xx).** Please send email for drill & tap details.

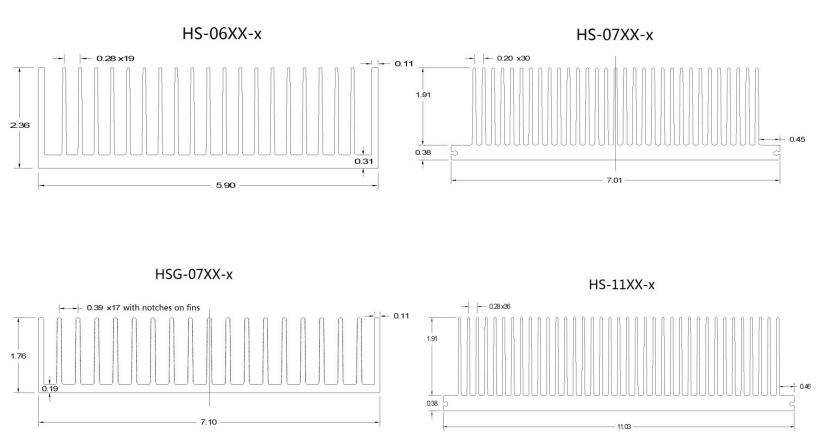
To specify the color of your heat sinks, attach the suffix-x:

-B black anodize

-C clear anodize

Key Specifications:

Forged from highly conductive aluminum Four engineered standard extrusion profiles CNC fly cut at the base to ensure the flatness at the interface side Lengths and holes are customized



STOCK No.	DIMENSIONS (inch)			FIN (Tapered, inch)				PHYSICAL PROPERTIES		
	Width	Height	Base Thickness	Spacing	Тор	Bottom	Height (inch)	Est. Weight (lbs/inch)	Heat Dissipation ⁽¹⁾ (°C/W/inch)	Surface Area (sq"/1")
HS-06XX	6	2.3	5/16	0.28	0.1	0.06	2	0.4	4.5	100
HS-07XX	7	2.3	3/8	0.2	0.1	0.06	1.9	0.65	3.2 ^③	135
HSG-07XX ^②	7	1.75	3/16	0.39	0.12	0.08	1.5	0.4	4.2	90
HS-11XX	11	2.3	3/8	0.28	0.12	0.08	1.9	1.1	3.7	160

1. Tested in ambient still air with room temperature

2. Fins are tapered with notches

3. Forced air units are suggested for HS-07XX and HS-11XX